

TITLE: METHODS OF FABRICATING SEMICONDUCTOR
SUBSTRATE-BASED BGA INTERCONNECTION

Inventor: Salman Akram
Serial No.: Not Yet Assigned
Docket No.: 3091.5US

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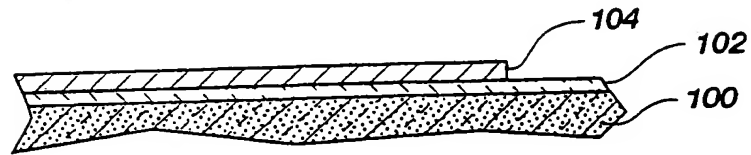


Fig. 1

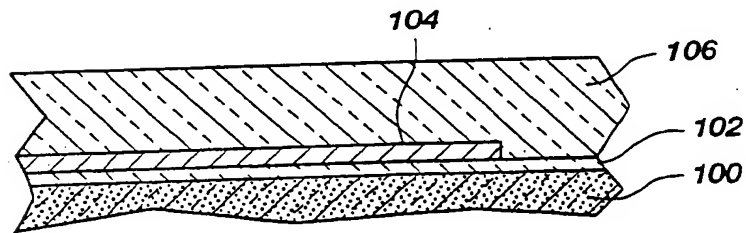


Fig. 2

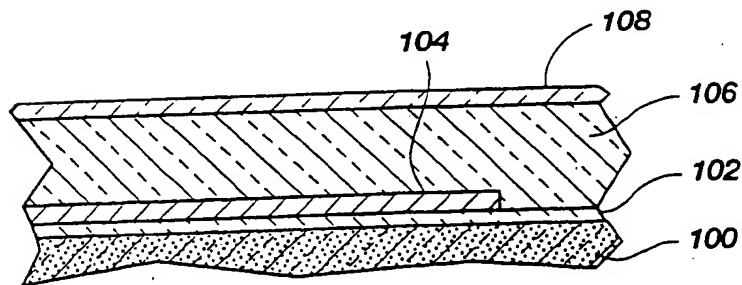


Fig. 3

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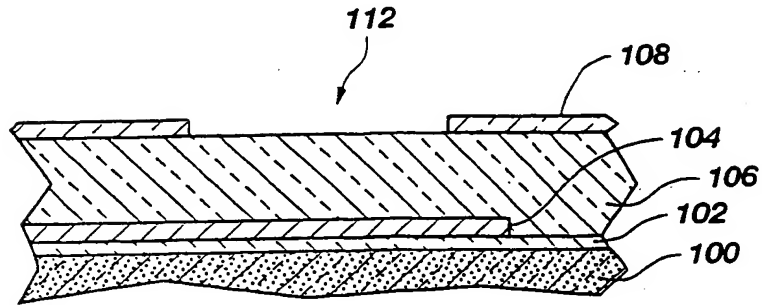


Fig. 4

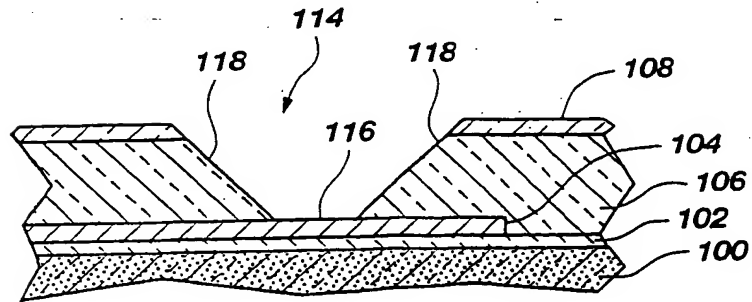


Fig. 5

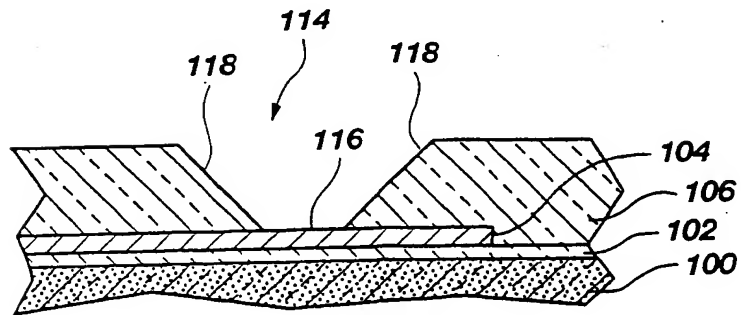


Fig. 6

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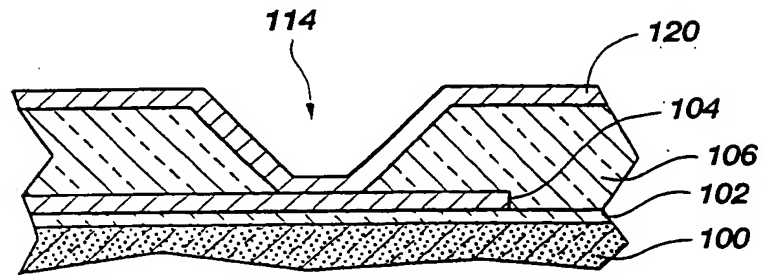


Fig. 7

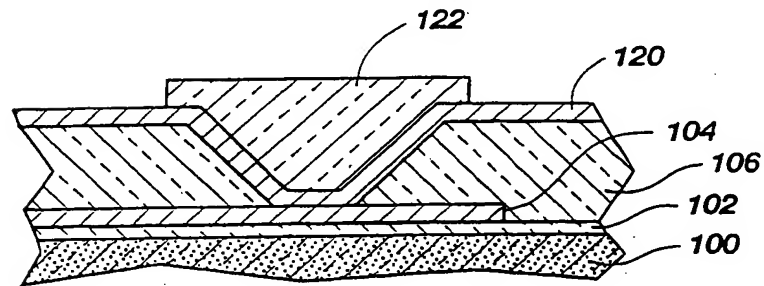


Fig. 8

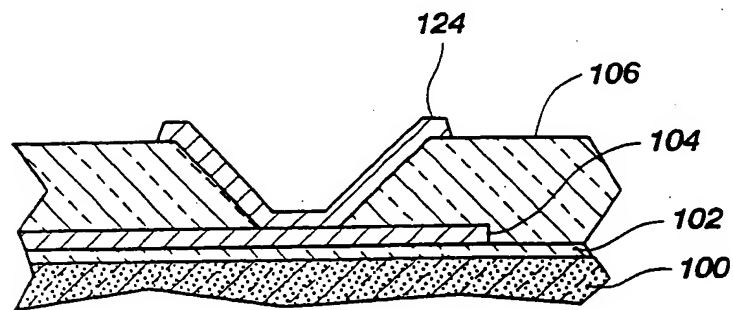


Fig. 9

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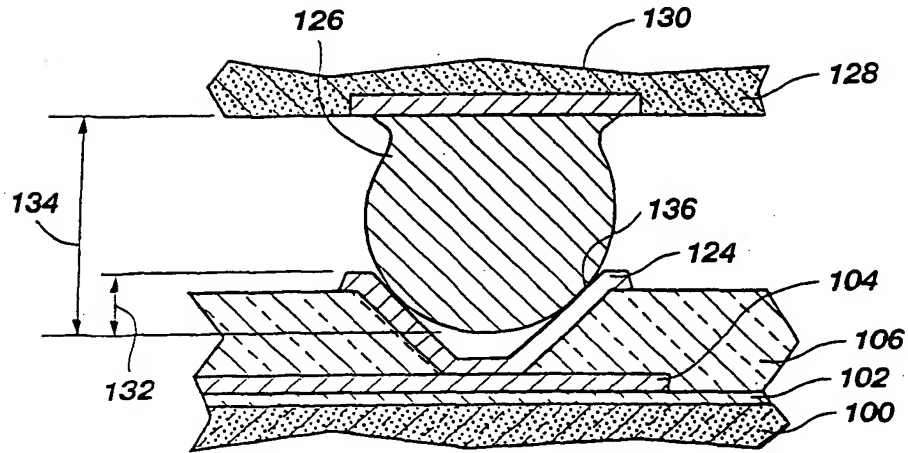


Fig. 10

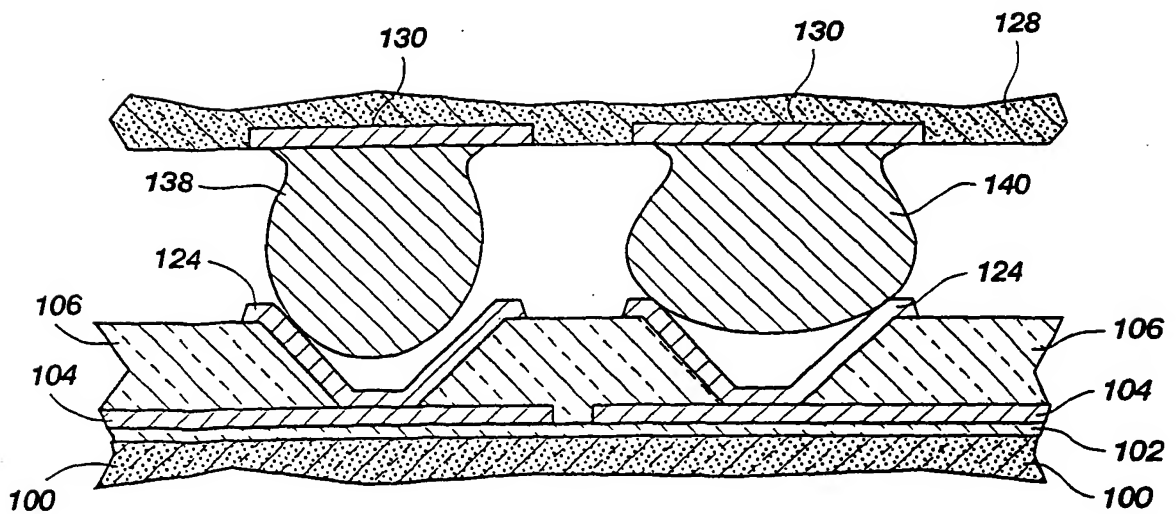


Fig. 11

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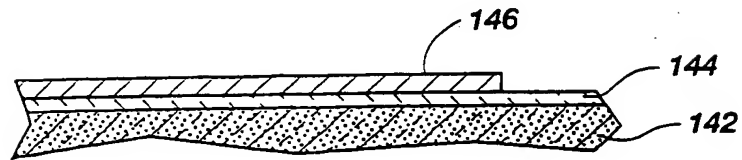


Fig. 12

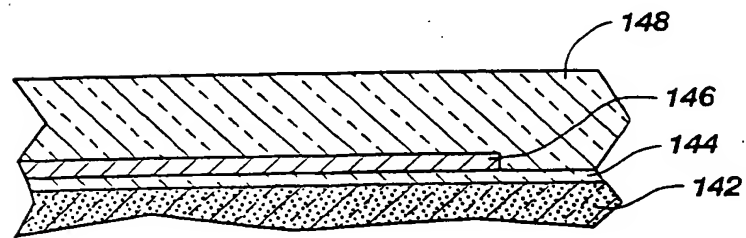


Fig. 13

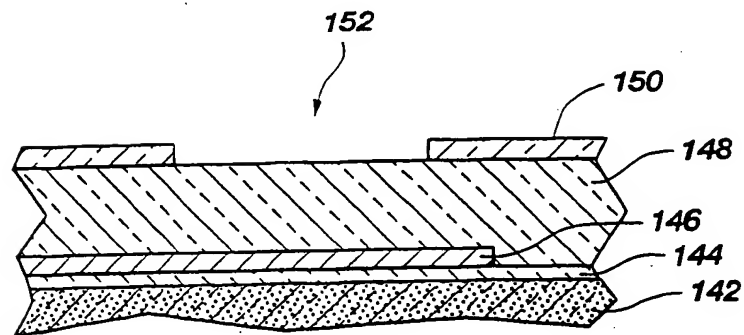


Fig. 14

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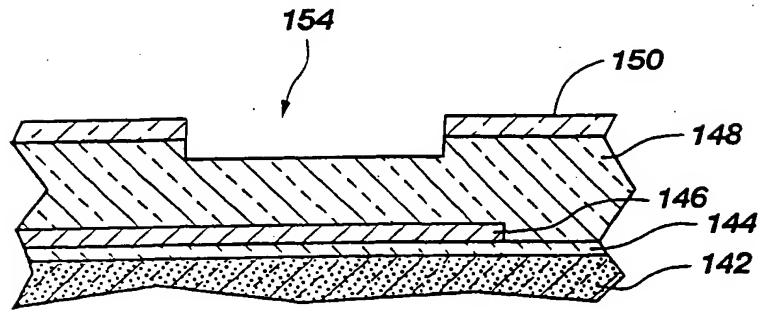


Fig. 15

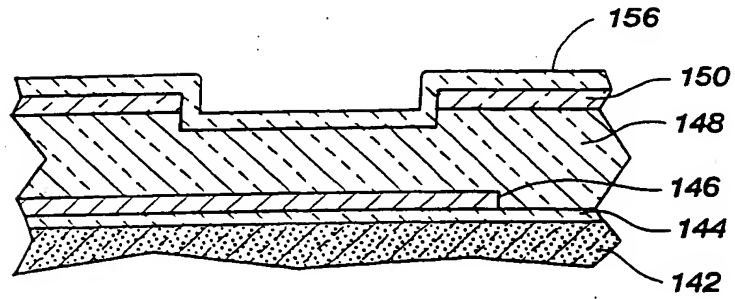


Fig. 16

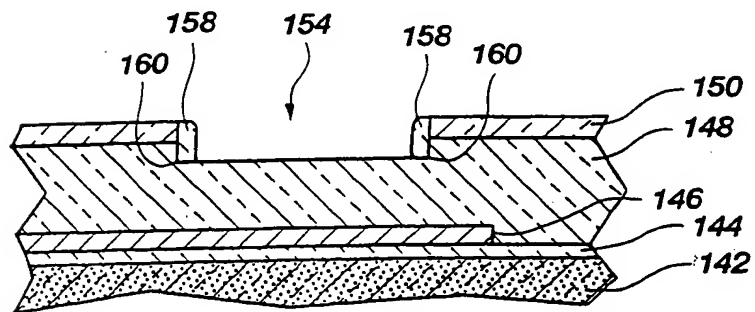


Fig. 17

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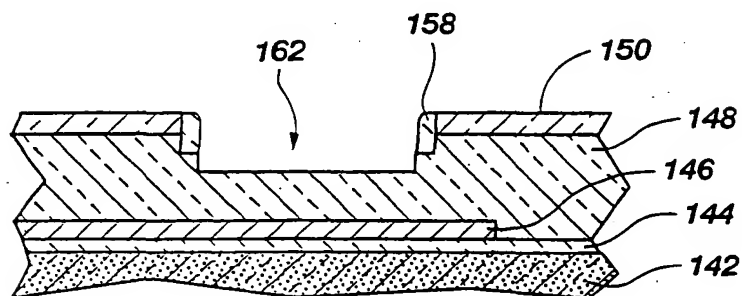


Fig. 18

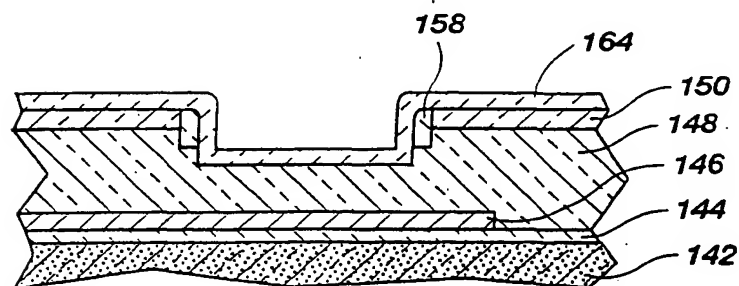


Fig. 19

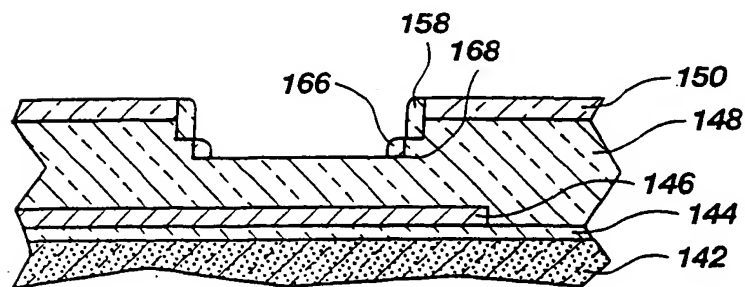


Fig. 20

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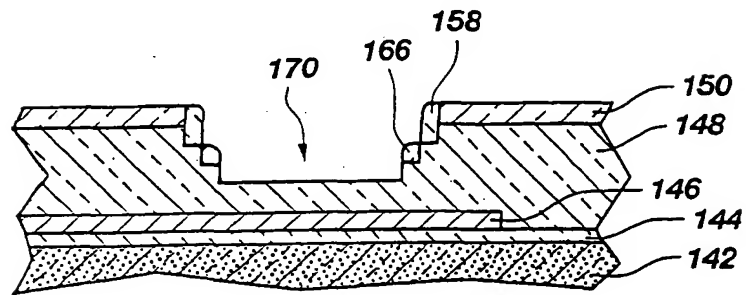


Fig. 21

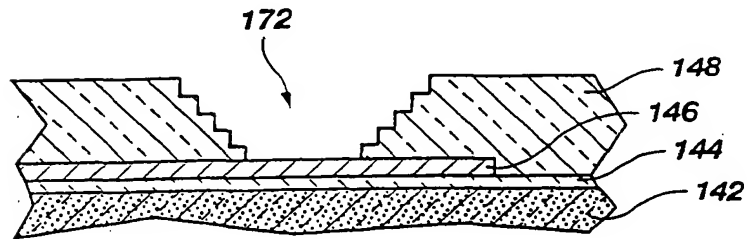


Fig. 22

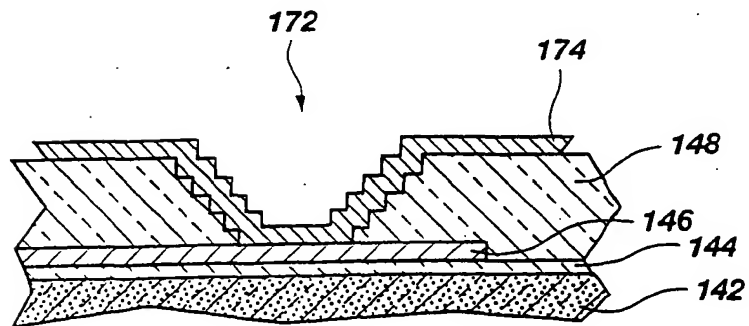


Fig. 23

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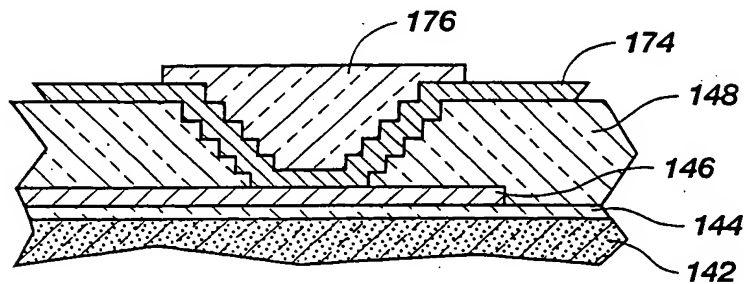


Fig. 24

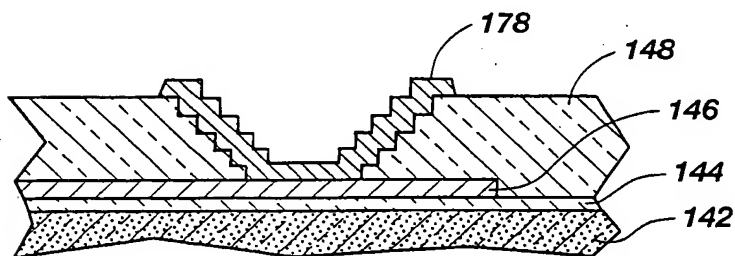


Fig. 25

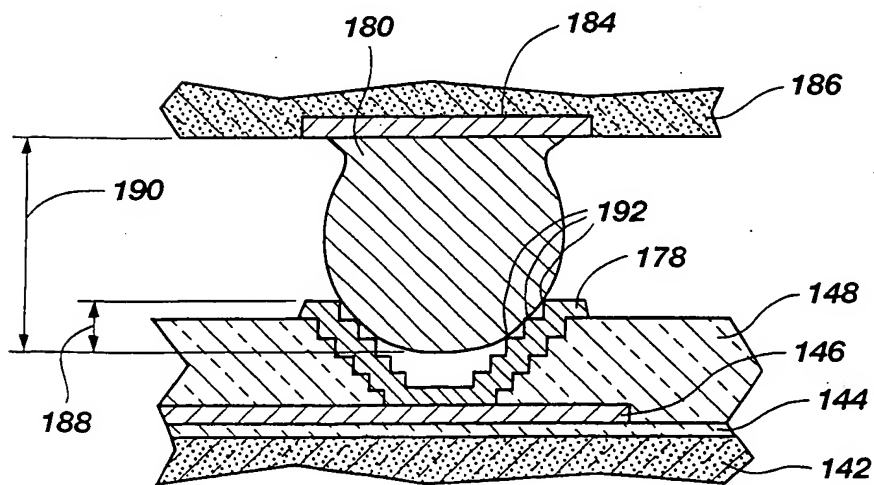


Fig. 26

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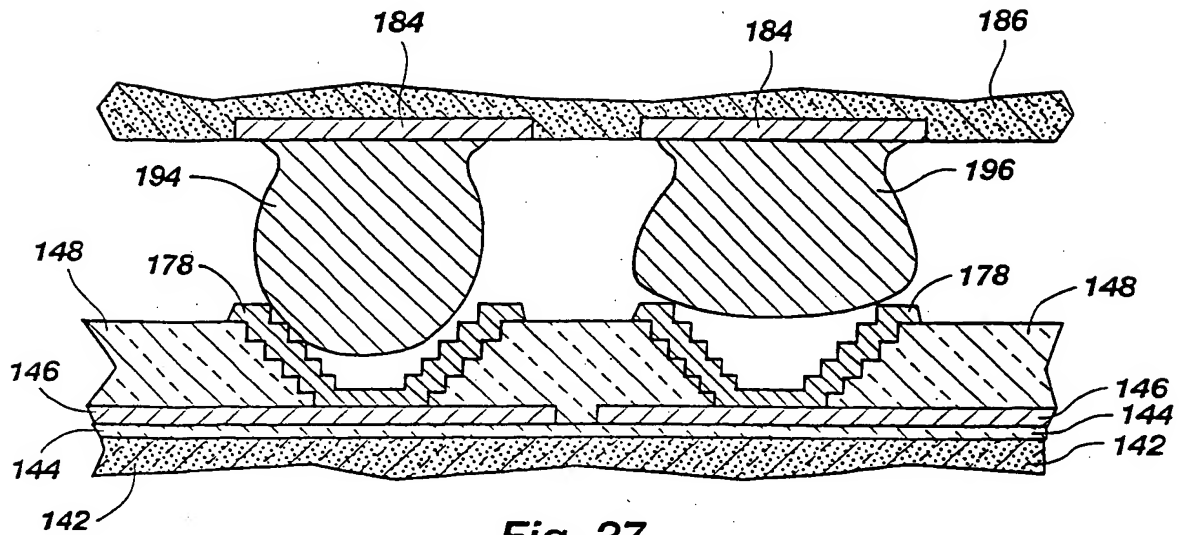


Fig. 27

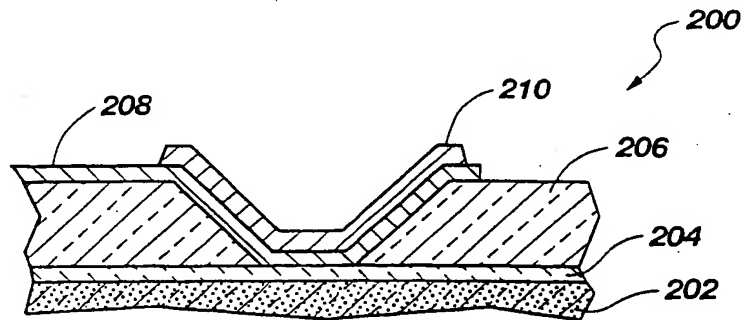


Fig. 28

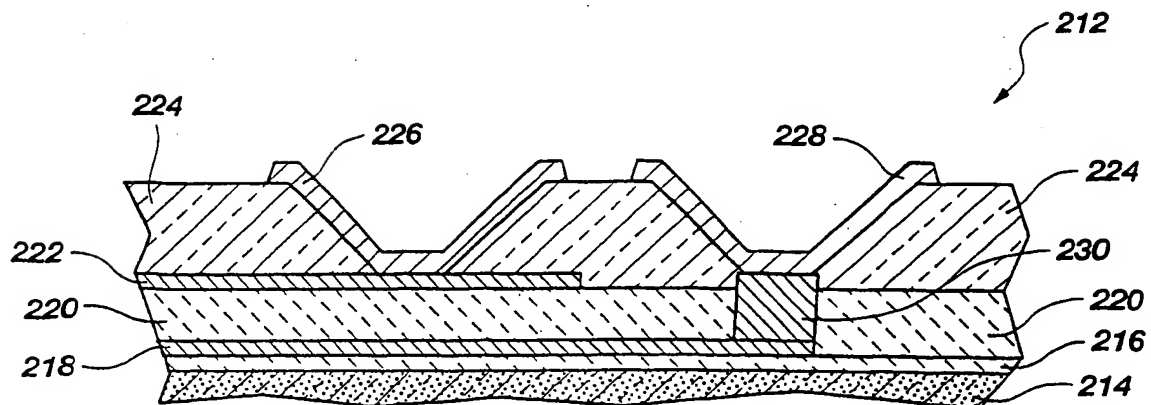


Fig. 29

This diagram shows a second embodiment of the device in cross-section. It features a top layer 300 with a textured surface. Below this layer are two rectangular blocks 302, which are positioned on a substrate 304. The substrate 304 has a curved, bulbous shape. The blocks 302 are separated by a gap. The entire assembly is supported by a base layer 306, which has a textured surface. The base layer 306 is shown in cross-section, revealing its internal structure. The label 308 points to the bottom edge of the base layer 306.

Fig. 32
(PRIOR ART)